

## **N-channel SiC power MOSFET**

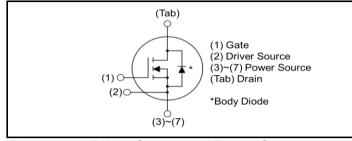
$V_{DSS}$	1200V
R <sub>DS(on)</sub> (Typ.)	160mΩ
<b>I</b> <sub>D</sub> <sup>*1</sup>	17A
$P_D$	100W

# Outline TO-263-7L (Tab)

#### Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

# ●Inner circuit



Please note Driver Source and Power Source are not exchangeable. Their exchange might lead to malfunction.

## Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- · Induction heating
- Motor drives

#### Packaging specifications

	Packing	Embossed tape
	Reel size (mm)	330
Type	Tape width (mm)	24
Туре	Basic ordering unit (pcs)	1000
	Taping code	TL
	Marking	SCT3160KW7

#### ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V <sub>DSS</sub>	1200	V
Continuous Drain current	$T_c = 25$ °C	I <sub>D</sub> *1	17	Α
Continuous Diam current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	12	Α
Pulsed Drain current		I <sub>D,pulse</sub> *2	42	Α
Gate - Source voltage (DC)		$V_{GSS}$	-4 to +22	V
Gate - Source surge voltage (t <sub>surge</sub> < 300ns)		V <sub>GSS_surge</sub> *3	-4 to +26	V
Recommended drive voltage		$V_{GS\_op}^{^{*4}}$	0 / +18	V
Junction temperature		T <sub>j</sub>	175	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +175	°C

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Faiametei	Symbol	Conditions	Min.		Max.	Offic
		$V_{GS} = 0V$ , $I_D = 1mA$				
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$T_j = 25^{\circ}C$	1200	-	-	V
vollago		T <sub>j</sub> = -55°C	1200	-	-	
		$V_{GS} = 0V, V_{DS} = 1200V$				
Zero Gate voltage Drain current	I <sub>DSS</sub>	T <sub>j</sub> = 25°C	-	1	10	μΑ
Diam current		T <sub>j</sub> = 150°C	-	2	-	
Gate - Source leakage current	I <sub>GSS+</sub>	$V_{GS} = +22V, \ V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	I <sub>GSS-</sub>	$V_{GS} = -4V$ , $V_{DS} = 0V$	ı	ı	-100	nA
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V, I_{D} = 2.5mA$	2.7	1	5.6	V
		$V_{GS} = 18V, I_D = 5A$				_
Static Drain - Source on - state resistance	R <sub>DS(on)</sub> *5	T <sub>j</sub> = 25°C	-	160	208	mΩ
		T <sub>j</sub> = 150°C	-	272	-	
Gate input resistance	$R_{G}$	f = 1MHz, open drain	-	18	-	Ω

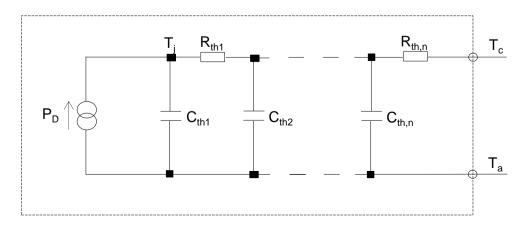
#### ●Thermal resistance

Parameter	Symbol	Values			Unit
raidilletei		Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	$R_{thJC}$	-	1.17	1.5	°C/W

● Typical Transient Thermal Characteristics

Symbol	Value	Unit
R <sub>th1</sub>	1.95×10 <sup>-1</sup>	
R <sub>th2</sub>	3.47×10 <sup>-1</sup>	K/W
R <sub>th3</sub>	5.60×10 <sup>-1</sup>	

Symbol	Value	Unit
$C_{th1}$	1.38×10 <sup>-3</sup>	
$C_{th2}$	1.40×10 <sup>-2</sup>	Ws/K
C <sub>th3</sub>	8.68×10 <sup>-3</sup>	



# ●Electrical characteristics (T<sub>a</sub> = 25°C)

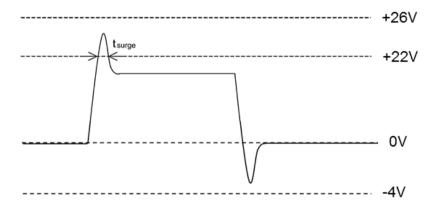
Parameter	Symbol	Conditions		Values		Unit
		Conditions	Min.	Тур.	Max.	Unit
Transconductance	<b>g</b> fs *5	$V_{DS} = 10V, I_{D} = 5A$	-	2.5	-	S
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	398	1	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 800V	-	41	ı	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	18	1	
Effective output capacitance, energy related	C <sub>o(er)</sub>	$V_{GS} = 0V$ $V_{DS} = 0V \text{ to } 600V$	-	45	ı	pF
Total Gate charge	Qg *5	$V_{DS} = 600V$ $I_{D} = 5A$	-	42	ı	
Gate - Source charge	Q <sub>gs</sub> *5	$V_{GS} = 18V$	-	10	ı	nC
Gate - Drain charge	Q <sub>gd</sub> *5	See Fig. 1-1.	-	22	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DS} = 600V$ $I_{D} = 5A$	-	3	ı	
Rise time	t <sub>r</sub> *5	$V_{GS} = 0V/+18V$	-	9	-	no
Turn - off delay time	t <sub>d(off)</sub> *5	$R_G = 0Ω$ , L = 750μH $E_{on}$ includes diode	-	14	ı	ns
Fall time	t <sub>f</sub> *5	reverse recovery $L_{\sigma} = 50 \text{nH}, C_{\sigma} = 10 \text{pF}$	-	9	-	
Turn - on switching loss	E <sub>on</sub> *5	See Fig. 2-1, 2-2, 2-3.	-	75	-	1
Turn - off switching loss	E <sub>off</sub> *5		-	7	-	μJ

## ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Values		
raiailletei	Symbol	Conditions	Min.	Тур.	Max.	Unit
Body diode continuous, forward current	I <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	ı	17	А
Body diode direct current, pulsed	I <sub>SM</sub> *2	11 <sub>c</sub> = 23 0	-	ı	42	А
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_D = 5A$	-	3.2	1	V
Reverse recovery time	t <sub>rr</sub> *5	$I_F = 5A$ $V_R = 600V$	-	11	ı	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 2500A/µs	-	108	ı	nC
Peak reverse recovery current	I <sub>rrm</sub> *5	$L_{\sigma} = 50$ nH, $C_{\sigma} = 10$ pF See Fig. 3-1, 3-2.	-	20	-	А

<sup>\*1</sup> Limited by maximum temperature allowed.

### \*3 Example of acceptable V<sub>GS</sub> waveform



Please note especially when using driver source that V<sub>GSS\_surge</sub> must be in the range of absolute maximum rating.

 $^{*}4$  Please be advised not to use SiC-MOSFETs with  $V_{GS}$  below 13V as doing so may cause thermal runaway.

\*5 Pulsed

<sup>\*2</sup>  $P_W \le 10\mu s$ , Duty cycle  $\le 1\%$ 

Fig.1 Power Dissipation Derating Curve

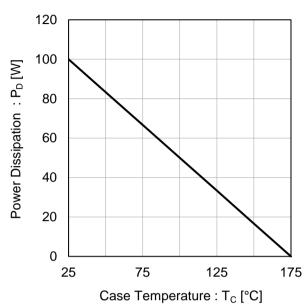


Fig.2 Maximum Safe Operating Area

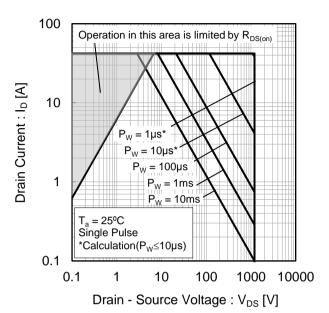


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width

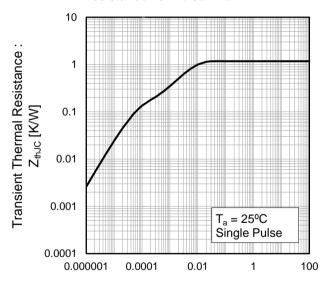


Fig.4 Typical Output Characteristics(I)

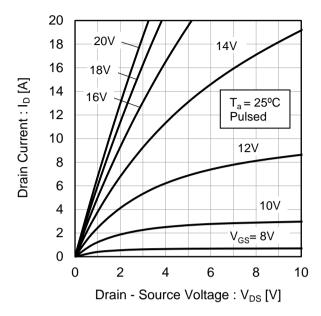


Fig.5 Typical Output Characteristics(II)

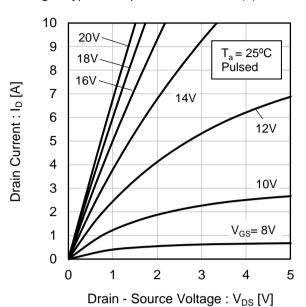
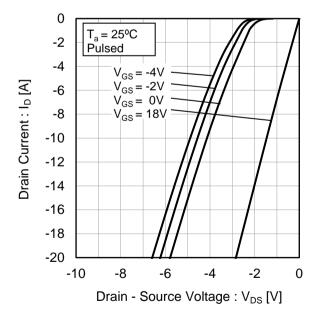
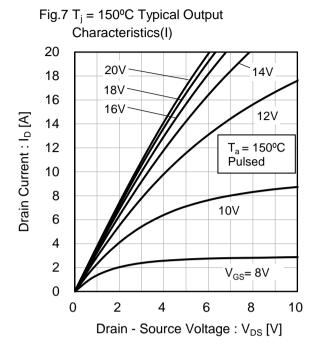


Fig.6 T<sub>i</sub> = 25°C 3rd Quadrant Characteristics



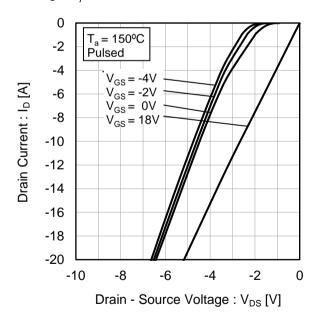
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Characteristics(II) 10 20V-9 14V 18V 8 12V 16V Drain Current : I<sub>D</sub> [A] 7 6 10V 5 4  $V_{GS} = 8V$ 3 2  $T_a = 150^{\circ}C$ 1 Pulsed 0 2 3 0 Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.8 T<sub>i</sub> = 150°C Typical Output

Fig.9 T<sub>i</sub> = 150°C 3rd Quadrant Characteristics



6 Body Diode Forward Voltage: Vsp [V]  $I_D=5A$ 5 4 3 2 T<sub>a</sub>= 150°C

Fig.10 Body Diode Forward Voltage

vs. Gate - Source Voltage

1  $T_a = 25^{\circ}C$ 0 -4 0 4 8 16 Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.11 Typical Transfer Characteristics (I)

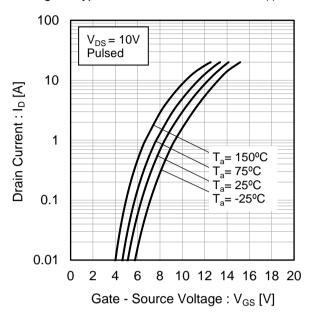


Fig.12 Typical Transfer Characteristics (II)

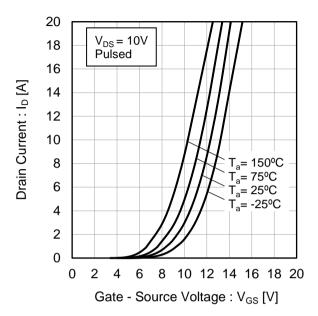


Fig.13 Gate Threshold Voltage vs. Junction Temperature

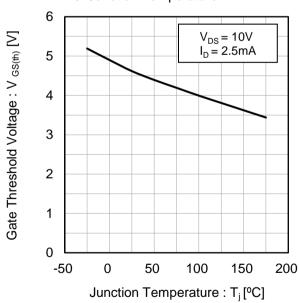
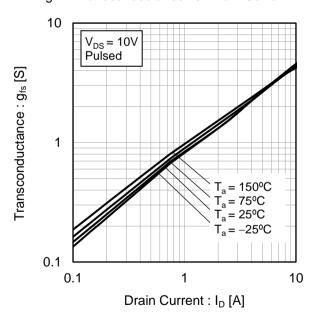


Fig.14 Transconductance vs. Drain Current



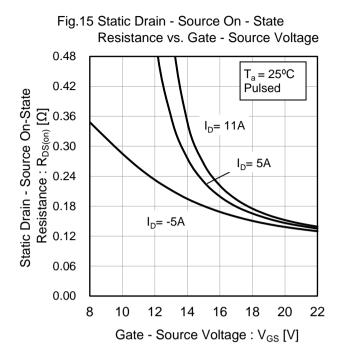
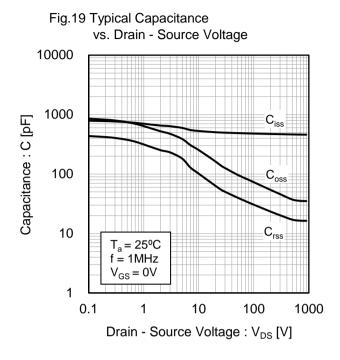


Fig.16 Static Drain - Source On - State Resistance vs. Junction Temperature 0.48  $V_{GS} = 18V$ 0.42 Pulsed Static Drain - Source On-State Resistance: R<sub>DS(on)</sub> [\(\text{O}\)] 8 0.36 0.30 0.24 0.18 0.12  $I_D = 11A$  $I_D = 5A$  $I_D = -5A$ 0.06 0.00 -50 0 50 100 150 200 Junction Temperature : T<sub>i</sub> [°C]

Fig.17 Static Drain - Source On - State Fig.18 Normalized Drain - Source Breakdown Resistance vs. Drain Current Voltage vs. Junction Temperature 1 1.04  $V_{GS} = 18V$ Static Drain - Source On-State 1.03 Pulsed Normalized Drain - Source Resistance: R<sub>DS(on)</sub> [Ω] Breakdown Voltage 1.02 0.1 1.01  $T_a = 150^{\circ}C$  $T_a = 125^{\circ}C$  $T_a^{\circ} = 75^{\circ}C$ 1.00  $T_a = 25^{\circ}C$  $T_a = -25^{\circ}C$ 0.99  $V_{GS} = 18V$ Pulsed 0.01 0.98 100 10 -50 0 50 100 150 Drain Current: I<sub>D</sub> [A] Junction Temperature : T<sub>i</sub> [°C]

200



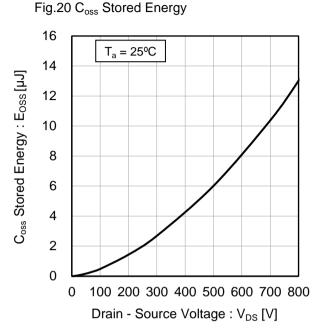
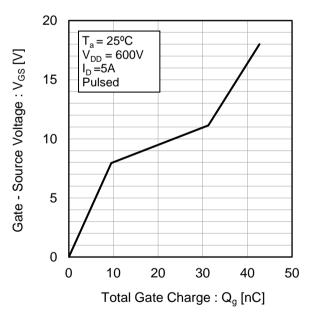


Fig.21 Dynamic Input Characteristics



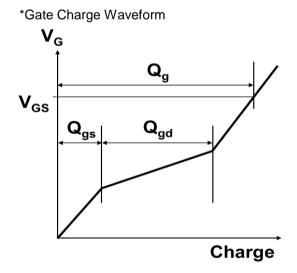


Fig.22 Typical Switching Time vs. External Gate Resistance

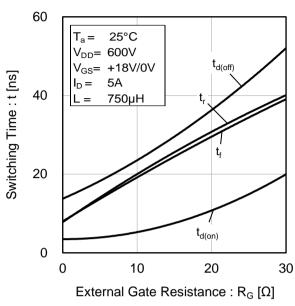


Fig.23 Typical Switching Loss vs. Drain - Source Voltage

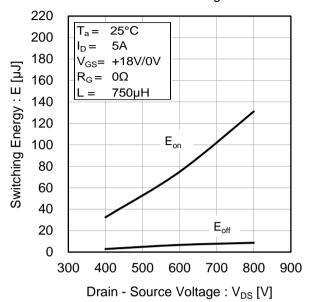


Fig.24 Typical Switching Loss vs. Drain Current

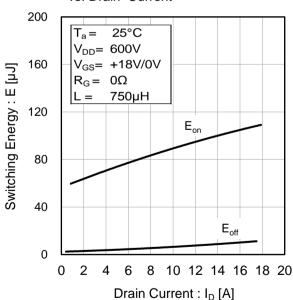
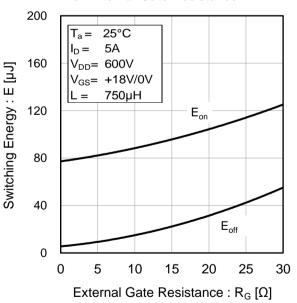


Fig.25 Typical Switching Loss vs. External Gate Resistance



#### Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

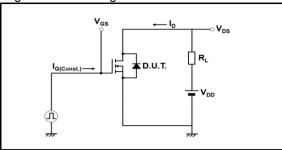


Fig.2-1 Switching Characteristics Measurement Circuit

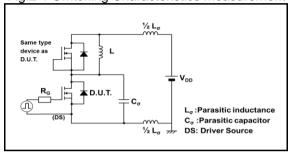


Fig.2-2 Waveforms for Switching Time

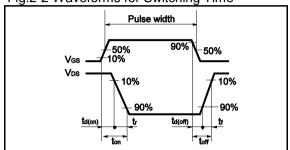


Fig.2-3 Waveforms for Switching Energy Loss

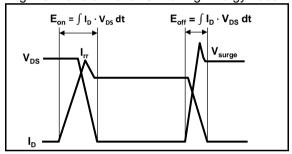


Fig.3-1 Reverse Recovery Time Measurement Circuit

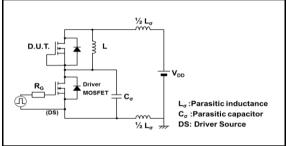
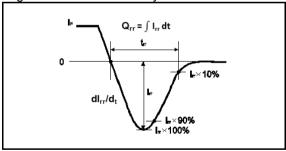


Fig.3-2 Reverse Recovery Waveform



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